

AMENDMENT UNDER 37 C.F.R. § 1.111
U.S. Application No. 09/751,844

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END supporting the transmission lines, between the dielectric substrate and each of the transmission lines in order to isolate the transmission lines a predetermined interval apart from the upper surface of the dielectric substrate.

a2 6. (Amended) A circuit board comprising: a dielectric substrate, a grounding surface formed on at least one surface of the dielectric substrate, and transmission lines formed on one surface of the dielectric substrate for transmitting electrical signals, wherein at least a portion of each of the transmission lines is isolated from the upper surface of the dielectric substrate to reduce an effective permittivity between the transmission lines and the grounding surface and reduce dielectric loss, and a cap which covers the transmission lines, one end of the cap being grounded to the grounding surface; and further comprising a plurality of dielectric supporters for supporting the transmission lines, between the dielectric substrate and each of the transmission lines in order to isolate the transmission lines a predetermined interval apart from the upper surface of the dielectric substrate.

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Cont 9. (Amended) A circuit board comprising: a dielectric substrate, a grounding surface formed on at least one surface of the dielectric substrate, and transmission lines formed on one surface of the dielectric substrate for transmitting electrical signals, wherein at least a portion of each of the transmission lines is isolated from the upper surface of the dielectric substrate to reduce an effective permittivity between the transmission lines and the grounding

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surface and reduce dielectric loss, and a cap which covers the transmission lines, one end of the cap being grounded to the grounding surface;

*A2
End*
and further comprising a plurality of supporters for supporting the transmission lines, between the dielectric substrate and each of the transmission lines in order to isolate the transmission lines a predetermined interval apart from the upper surface of the dielectric substrate, wherein an inside of the cap is in a vacuum state; and wherein the transmission lines are installed on one surface of the dielectric substrate, the grounding surface is formed on an opposite surface of the dielectric substrate, and a conducting electrode is installed, one end of which is connected to the cap and the other is grounded to the grounding surface through the dielectric substrate so that the cap is grounded to the grounding surface.

Please add the following new claims:

act 22. (New) The circuit board of claim 2, wherein each of the plurality of dielectric supporters is formed of a polymer to reduce electrical loss.

23. (New) The circuit board of claim 6, wherein each of the plurality of dielectric supporters is formed of a polymer to reduce electrical loss.
